

for industrial applications

Addressing the growing demand for efficient, high-voltage power conversion and motor drives, Nexperia's IGBTs feature a robust and cost-effective carrier stored trench-gate (CSTBT) advanced field-stop (FS) construction. Delivering high ruggedness reliability and enhanced inverter power density for industrial applications.

Design Benefits

- > Low conduction and switching losses
- > High ruggedness reliability
- Stable and tight parameters for easy parallel operation
- Maximum junction temperature of 175 °C
- Fully rated as a Soft Fast Reverse Recovery Diode
- > 5 µs short circuit capability (For M3)
- Enabling outstanding system efficiency and reliability

Key technical features

- Ultra low diode Vf
- > Ultra low IGBT turn off loss
- > Trade off for total power loss



Key applications

- Industrial motor drives particularly 5 <> 20 kW (20 kHz) servo motors
 - robotics, elevators, operating grippers, in-line manufacturing
- Power inverters
 - Uninterruptible Power Supply (UPS)
 - photovoltaic (PV) strings
 - EV-charging
- Induction heating, welding



600 V products

Type name	Voltage/ Current@ Tc=100°C	IGBT type	Copak Diode rating	SCWT	Package	Release date
NGW30T60M3DF	600/30	MS	- Full	5us	TO-247-3L	Summer 2023
NGW40T60H3DF	600/40	HS				
NGW50T60M3DF	600/50	MS		5us		
NGW75T60H3DF	600/75	HS				

650 V products

Type name	Voltage / Current @ Tc=100oC	IGBT type	Copak Diode rating	SCWT	Package	Release date
NGW30T65M3DF	650/30	MS	- Full	5us	TO-247-3L	Q4 2023
NGW40T65H3DF	650 / 40	HS				
NGW50T65M3DF	650/50	MS		5us		
NGW75T65H3DF	650 / 75	HS				

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